

Plug-Compatible Modular Thermal Management Packages

RELATED PATENT APPLICATIONS

This application is a United States utility patent application based on
Provisional Patent Application 60/416,651 entitled "Thermal Packaging System for
Small-Scale Solid Oxide Fuel Cells" filed on October 7, 2002.

BACKGROUND OF THE INVENTION

1. Field of the Invention

In one aspect, this invention relates to a device that allows the easy
replacement of a power source which supplies energy to operate small electronic
devices. In another aspect, the plug compatible module is incorporated as a thermal
management package that can be plug-replaceable as needed. Furthermore, the
invention concerns a method for the generation of power by such miniature solid
oxide fuel cells (SOFC). Yet another aspect of this invention is to provide a portable
moderate-to-high temperature heat source based on combustion. Still another
aspect of this invention involves miniature chemical reactors, which produces an
actual desired chemical reaction product.

2. Background and Related Art

Fuel cells are one of the cleanest and most efficient technologies for power
generation available. Since there is no combustion, there are none of the pollutants
commonly produced by furnaces and boilers. Much written material on the topic of
fuel cells is concerned with generation of large quantities of power, such as would be
required by utilities supplying power to homes and industry.

Searching patent and other literature on solid oxide fuel cells uncovers large amounts of material. There has been volumes written about solid oxide fuel cells with regard to their use in power plants, home heating and power systems, and many industrial applications. The idea of a miniature, modular energy system is not found, particularly as pertaining to plug-compatibility.

Regarding modularity, Elangovan et al in US patent 5,480,738 discusses fuel cell modules with mention of their interconnection. The modules of '738 are not in any small or plug compatible form, as are the devices of the instant invention. Likewise, Gillett et al. in US patent 5,741,605 discusses a solid oxide fuel cell with removable modular stack configurations. Far from being miniaturized, the removable modules are parts of an electrical power plant.

For the purposes of the present invention, miniaturized, plug-compatible thermal management packages represent an easily-replaceable, plug-compatible means to supply power to a relatively small electronic device, which device may be compact and portable. In this way, the easily-replaceable solid oxide fuel cell of this invention is analogous to batteries that supply power to such devices. Such devices include personal computers, PDAs, cellular telephones, portable global positioning systems (GPS) and the like. Their plug-compatibility is analogous to light bulb replacement; especially quartz-halogen light bulbs.

Summary of the invention

The current invention relates to a miniaturized, easily replaceable, plug compatible thermal management package sealed in at least one insulated envelope comprising

- a) at least one air inlet;
- b) at least one fuel inlet;
- c) a plurality of connectors to receive and supply electric power;
- d) an exhaust outlet

and, optionally

e) a counter-flow heat exchanger; and

f) an ignitable catalytic combustor;

combined with a second plurality of connectors which are plugged into a mating socket to supply and accept both electrical power and gas flow.

5 In such a system, the recovery of thermal energy is by means of a counterflow heat exchanger, efficient thermal insulation, combustion of residual fuel, and cell isolation design with a minimal heat loss to the surroundings, and which provides high performance and efficiency to the system. Heat loss minimization by the thermal insulation barrier can comprise, for example, a vacuum multi-foil
10 insulation (VMI) envelope, or evacuated or gas-filled fibrous ceramic insulation or Aerogel-type material. The various means of energy saving and recovery are enveloped in hermetic packaging. The different insulations can be combined in a particular thermal management system if they are compatible. In the thermal management system of this invention an electrical igniter connector is necessary to
15 initiate the start-up sequence.

The thermal packaging schemes embodied in the present invention for small-scale power, heat or chemical generation are embodied by easily replaceable, inexpensive plug-compatible modular thermal management packages comprising at least one hermetic envelope made of quartz, glass, metals with low thermal
20 expansion properties such as ferritic steel or nickel-based super-alloys, and ceramic electrolytes and anode/cathode materials which function as the energy component of a portable power device.

A metal for connector feed-throughs that can bond to the quartz envelope would be molybdenum or tungsten with an oxide surface that can withstand the
25 operating temperature and any other physical limitations of the SOFC unit of this invention. The feed-through connectors would be similar in nature as those found in quartz halogen light bulbs.

Key to the success of the thermal management package of a plug-compatible packaging concept that allows the fuel cell unit or other module of this
30 invention to operate for a limited period of time after which time they will need replacing at periodic intervals while keeping ancillary systems intact.

Further details, description, and discussion on the operation of the plug-compatible modular thermal management packages of this invention follow below.

BRIEF DESCRIPTION OF THE DRAWINGS

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Figure 1 depicts a single envelope design of a SOFC of this invention with reactants inlet, exhaust outlet, and catalytic combustor shown

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Figure 2 depicts a double envelope design of a SOFC of this invention with external connections shown

Figure 3 shows compacted cross-sectional views of a double envelope design of a SOFC of this invention in both rectangular and circular shapes

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Figure 4A depicts a compacted cross-sectional view of a disc-shaped SOFC of this invention.

Figure 4B depicts a top view of a disc-shaped SOFC of this invention.

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Figure 5 shows an arrangement of a plug-compatible thermal management package that generates heat from combustion.

Figure 6 shows a plug-compatible thermal management package that performs chemical processing at elevated temperatures.

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DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

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As seen in Figure 1, the modular thermal management package **1** of this invention is analogous to a quartz-halogen light bulb where a hot filament is kept isolated from its surroundings by being enclosed in a quartz envelope that is able to withstand elevated temperature operation. In those bulbs, the external envelope **10** contains a halogen substance designed to enhance the lifetime of the extremely hot filament that it contains. Seen in Figure 1 is a layer of vacuum insulation **16** which

surrounds the SOFC **14** inside the envelope **10**. In the present invention, the envelope contains an insulative environment **16** such as ceramic fibers, low density Aerogel, or vacuum conditions to minimize heat loss to the surroundings.

5 Depicted in Figure 2, is an SOFC with a double envelope design. The modular thermal management package **1** of this embodiment provides power supplied by incorporating two electrode connectors **11** which connect the envelope **10** for supplying power to external devices. The packaging scheme for the replaceable, modular thermal packaged **1** will have different, distinctive features from a quartz-halogen bulb such as a catalytic combustor **20** and heat exchanger **15** 10 that are required for its operation. The catalytic combustor **20** can be integrated directly into the SOFC **14** exhaust section to burn residual fuel.

Present in the double envelope design of Figure 2 is a layer of vacuum insulation **16** which surrounds the SOFC **14** inside the envelope **10**. In the double envelope design, there is an inner envelope **17** which is enclosed outer envelope **10**. 15 Another feature of the double envelope design of figure 2 includes reflective coatings **18** which surround the inner envelope **17**

Figures 1 and 2 also show several requirements for SOFC operation including reactant supply and product exhaust **12**, at least two electrical connections **11**. Thermal management mechanisms of this invention may include a vacuum 20 environment **16** or fibrous low density high-temperature ceramic insulation surrounding the SOFC **14**. Or, alternatively, Aerogel or Aerogel-like insulating materials as well as vacuum multifoil insulation (VMI) may be used as insulation surrounding each SOFC **14**.

It may be noted that Aerogel is a porous material with extreme microporosity 25 made by high-temperature and pressure supercritical drying of a silicon dioxide gel comprising a colloidal silica structural units filled with solvents. The material is 99.8% air and is 1,000 times less dense than glass. Multifoil vacuum insulation, or vacuum multifoil insulation (VMI) is a material designed for thermal battery needs of advanced defense systems. It is designed to increase the operating life of a thermal 30 battery from 2-3 hours to 6-8 hours

Figure 1 is a diagram of one preferred embodiment of the modular thermal management package **1** of the present invention. As shown in Figure 1, the external envelope **10** may be made from a variety of materials including glass or quartz, but quartz is preferred since it is operable at higher temperatures (up to 800 degrees C) than glass, which operates up to a temperature of 500 degrees C. This choice of material is analogous to that of the quartz-halogen lamp, which uses a tungsten filament encased in a quartz envelope to withstand high temperatures.

Also shown in Figure 1 are the electrical feed-throughs **11** for cell operation. These can be similar to the quartz-halogen lamp design, but for reactant supply and product exhaust **12**, the feed-throughs must be hollow tubes and be compatible with the reactants and products used for operation of a particular modular thermal management package **1**.

It should be noted that if the reactants in a particular SOFC **14** must be kept separate they will each need a reactant line **12a**. Fuels considered as possible for use in the SOFC **14** of this invention are hydrogen, ammonia, methanol, a low molecular weight hydrocarbon, or a reformat mixture. In this invention, a low molecular weight hydrocarbon will have a molecular weight less than or equal to 100 grams/mole. A preferred fuel is methanol or propane. Separate fuel lines **12a** will be needed for fuel and air.

If the reactants are mixable, a simpler configuration of a single inlet and exhaust **12** will be used. In a preferred embodiment, the feed-through **13** will be compatible (have similar or matching thermal expansion coefficients and having sealing capability when joined together) with the external envelope **10** construction material. Having similar thermal expansion coefficients and the capability to form the hermetic seal are necessary to maintain vacuum or gas tight conditions inside the envelope **10**. In order to conserve thermal energy in the product stream which emerges from the SOFC **14** at the cell temperature, the heat exchanger **15** is important. The heat exchange operation takes place before the exhaust products leave the SOFC**14**.

Heat exchange takes place in the counterflow heat exchanger **15** where the product line **12b** is in direct contact with the reactant line **12a** along their streams.

This permits thermal energy in the product stream to be transferred to the reactants, thus heating the reactants and cooling the products. This cools the products before they reach the envelope **10** seal at the base of the thermal package thus relieving some thermal stress on the modular thermal management package **1**. The amount of heat exchanged between the reactants and the products will depend on the degree of heat loss tolerated for a specific cell design.

The environment surrounding the SOFC **14** shown in Figure 4 and contained within the disc-shaped inner envelope **30** of this invention performs a thermal management function that allows the SOFC **14** to operate at temperatures between 500 C and 850 C. while maintaining the thermal package outer envelope **10** at a temperature level consistent with its surroundings. The modular thermal management package **1** will be generating waste heat from its operation. In addition, the modular thermal management package **1** may incorporate features to catalytically combust the effluent stream exiting the cell, which contains unreacted fuel and oxygen.

Insulation for cell operation is necessary because the heat generated by the device is insufficient to keep it at high temperatures if exposed to air or other high-convection surroundings. Radiation heat loss may also play a larger role as the size of the modular thermal management package **1** is reduced. One method of providing such insulation is to evacuate the outer envelope **10** while maintaining a hermetic seal around it. If the surface of the outer envelope **10** is coated with a thin film of gold or other low emissivity as a reflective coating **18**, the heat radiation effects can be minimized and the convection heat loss can be virtually eliminated. However, when the cell is operating at 500 degrees C or higher, radiation heat loss will be significant for smaller cells in the power range below 100 Watts, and more specifically below 10 Watts.

Another means of insulating the SOFC **14** from its surroundings is to pack the space between it and the envelope **10** with a fibrous, low-density high-temperature ceramic insulation. This means of insulation is preferred when the fuel cell unit is at the high end of its operating range, at about 10 Watts. The range of power that the modular thermal management package **1** will produce will range from about 10 milli-

watts to about 10 watts. Replacing the air inside the envelope **10** with a higher molecular-weight gas causes an increase in the thermal resistance between the SOFC **14** and envelope**10** occurs and reduces the heat flow out of the modular thermal management package **1**. By using fibrous ceramic insulation and a selected
5 gas, the thermal resistance can be increased while relaxing the need for vacuum conditions on the inside of the envelope**10**, resulting in a more practical arrangement for the thermal packaging system for small-scale the modular thermal management package **1**.of this invention.

Yet another means of insulating the SOFC **14** is to maintain a tight vacuum
10 within the envelope **10**. Alternately, an inner and an outer quartz (or glass) envelope can be used. Each of the vacuum-facing glass surfaces is metalized to reduce infrared radiation heat transfer, after which the SOFC**14** is placed into the envelope **10** and the space between the inner and outer envelopes would be evacuated.

The envelopes of this invention are maintained longer and maintain at a
15 higher level of thermal isolation for the SOFC**14** and performance of the modular thermal management package **1**. Gettering can be provided by a pellet of material specifically formulated to adsorb residue gasses inside the vacuum envelope **10**.

The configurations described above explain the use of miniaturized modular thermal management packages **1** of this invention as easily replaceable energy
20 sources that are spent and interchanged as easily as are quartz/halogen light bulbs. As a miniaturized unit or module, its size may range from about 0.1 to about 10 inches.

Another embodiment of the instant invention is a disc-shaped unit shown in Figure 4 whose envelope **30** is comprised of an upper disc **31**, a center washer **32**,
25 and a lower disc **33** bonded together and forming a cavity in the center of a disc-shaped fuel cell **34**. In this embodiment a plurality of feed-throughs **35** are necessary including supply lines, exhaust lines, and electrical lines.

Figure 3 shows cross-sectional views of circular 3a and rectangular 3b packaging arrangements for two of double envelope SOFC **14** units of this invention.
30 In both of these views, the SOFC **14** is surrounded by two glass envelopes **10**. The SOFC **14** of Figure 3b on the right is enclosed in a double glass envelope **40**. In

either or both of these designs, a vacuum interior can be created with appropriate sealing technology. In addition, low-density fibrous ceramic insulation, Aerogel, VMI and the like can be used on the top, bottom, and around the perimeter of the modular thermal management package **1** for insulation. In certain cases, a specified gas such as carbon dioxide or Argon, could also be used with the insulative materials to improve the thermal isolation. It is important that the disc-shaped SOFC **34** inside the envelope **10** is centered in the disc for vacuum-insulated devices.

Such centering is done by thin, (or small-diameter) protrusions of not more than 0.040 inches (about 1 mm) coming out of the perimeter of the disc-shaped SOFC **34** wall to make contact with the outside washer **32**. Alternatively, the supply and exhaust lines **12** (including both **12a** and **12b**) may be substantial enough to support the modular thermal management package **1**.

A counterflow design should be used for the supply line **12a** and the exhaust line **12b**. to recover the thermal energy in the product stream. If this supplies too much heat recovery and excess energy must be dissipated to the environment, the supply line **12a** and exhaust line **12b** could be re-routed to different locations. This would result in exhaust leaving the modular thermal management package **1** with substantial thermal energy. This may prove feasible if other losses, such as conduction and radiation, can be minimized.

Figure 4 depicts a modular thermal management package **1** of this invention in a flat disc configuration. In figure 4a, a disc shaped SOFC **34** surrounded by an outer glass envelope **10**. The flat disc configuration as seen in figure 4A also includes an integrated heat exchanger **36** and combustor **20** (not shown) as part of the flat disc configuration sofc **34** of the invention. The flat arrangement as shown in Figures 4a and 4b are applicable to larger surface applications that require a disc-shaped power source whose space constraints require thin, flat packaging of a modular thermal management package **1**.

Figure 5 depicts a modular thermal management package **1** that contains a unit that generates heat by burning a fuel in a catalytic combustor **20** which is ignited by a heater coil adjacent to the combustor **20**. The heat product is emitted through exhaust **12b**. An alternate arrangement for the combustion reaction depicted in

Figure 5, but not shown, is to have two reactant tubes and one exhaust line. In this manner, separate air and fuel lines can be used by the device.

The modular thermal management package 1 depicted in Figure 6 is miniature chemical reactor. These reactions can be endothermic and may take place at moderate or high temperatures. In this invention, moderate temperatures will range from about 200-500 degrees C, and high temperature will signify temperatures from 500 to 1000 degrees C. Examples of moderate temperature chemical reactions in this category are the decomposition of ammonia and the water-gas shift reaction.

In the water-gas shift reaction, entering the modular thermal management package 1 into inlet 12a are carbon monoxide (CO) and water (H₂O) which are converted, in the presence of a high temperature catalyst, to hydrogen (H₂) and carbon dioxide (CO₂)

DISCUSSION

The above presents a description of the best mode contemplated of carrying out the present invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains to make and use this invention. This invention is, however, susceptible to modifications and alternate constructions from that discussed above which are fully equivalent. Consequently, it is not the intention to limit this invention to the particular embodiments disclosed. On the contrary, the intention is to cover all modifications and alternate constructions coming within the spirit and scope of the invention as generally expressed by the following claims, which particularly point out and distinctly claim the subject matter of the invention: